

Schottky Barrier Diode NSR02L30NXT5G

These Schottky barrier diodes are optimized for low forward voltage drop and low leakage current. The DSN2 (Dual Silicon No-lead) package is a chip level package using solderable metal contacts under the package similar to DFN style packages. The DSN style package enables 100% utilization of the package area for active silicon, offering a significant performance per board area advantage compared to products in plastic molded packages. The low thermal resistance enables designers to meet the challenging task of achieving higher efficiency and meeting reduced space requirements.

Features

- Very Low Forward Voltage Drop 400 mV @ 10 mA
- Low Reverse Current 0.20 μA @ 10 V VR
- 200 mA of Continuous Forward Current
- Power Dissipation of 312 mW with Minimum Trace
- ESD Rating - Human Body Model: Class 3B
 - Machine Model: Class C
- Very High Switching Speed
- Low Capacitance CT = 7 pF
- This is a Halide-Free Device
- This is a Pb-Free Device

Typical Applications

- LCD and Keypad Backlighting
- Camera Photo Flash
- Buck and Boost dc-dc Converters
- Reverse Voltage and Current Protection
- Clamping & Protection

Markets

- Mobile Handsets
- MP3 Players
- Digital Camera and Camcorders
- Notebook PCs & PDAs
- GPS

MAXIMUM RATINGS

Rating		Symbol	Value	Unit
Reverse Voltage	Reverse Voltage		30	V
Forward Current (DC)		IF	200	mA
Forward Surge Current (60 Hz @ 1 cycle)		I _{FSM}	4.0	Α
ESD Rating:	Human Body Model Machine Model	ESD	>8.0 >400	kV V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

30 V SCHOTTKY **BARRIER DIODE**





(0201)CASE 152AA



= Specific Device Code M = Date Code

ORDERING INFORMATION

Device	Package	Shipping†
NSR02L30NXT5G	DSN2 (Pb-Free)	5000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

NSR02L30NXT5G

THERMAL CHARACTERISTICS

Characteristic	Symbol	Min	Тур	Max	Unit
Thermal Resistance Junction-to-Ambient (Note 1) Total Power Dissipation @ T _A = 25°C	R _{θJA} P _D			400 312	°C/W mW
Thermal Resistance Junction-to-Ambient (Note 2) Total Power Dissipation @ T _A = 25°C	R _{θJA} P _D			170 735	°C/W mW
Storage Temperature Range	T _{stg}			-40 to +125	°C
Junction Temperature	TJ			+150	°C

- Mounted onto a 4 in square FR-4 board 10 mm sq. 1 oz. Cu 0.06" thick single sided. Operating to steady state.
 Mounted onto a 4 in square FR-4 board 1 in sq. 1 oz. Cu 0.06" thick single sided. Operating to steady state.

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic		Symbol	Min	Тур	Max	Unit
Reverse Leakage	(V _R = 10 V) (V _R = 30 V)	I _R			0.2 3.0	μΑ
Forward Voltage	(I _F = 10 mA) (I _F = 200 mA)	V _F			0.40 0.58	V
Total Capacitance	(V _R = 5.0 V, f = 1 MHz)	СТ		7.0		pF

NSR02L30NXT5G

TYPICAL CHARACTERISTICS

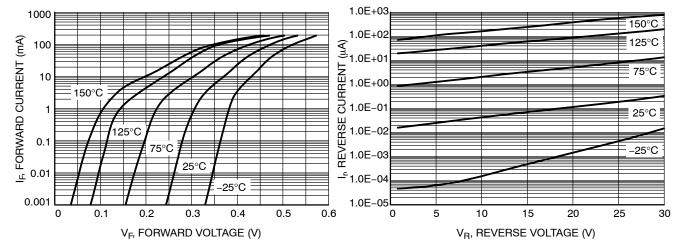


Figure 1. Forward Voltage

Figure 2. Leakage Current

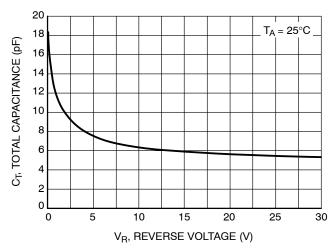


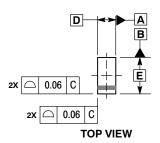
Figure 3. Total Capacitance

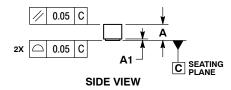


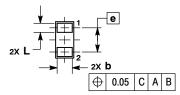


DSN2, 0.6x0.3, 0.4P, (0201) CASE 152AA **ISSUE B**

DATE 30 APR 2017

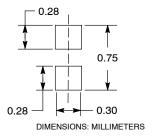






BOTTOM VIEW

MOUNTING FOOTPRINT*



See Application Note AND8398/D for more mounting details

NOTES

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS.

	MILLIMETERS			
DIM	MIN	MAX		
Α	0.24	0.30		
A1	0.00	0.01		
b	0.20	0.22		
D	0.30 BSC			
F	0.60 BSC			

0.40 BSC

0.10 0.12

GENERIC MARKING DIAGRAM1*

PIN 1 XXXX YYY



GENERIC

MARKING DIAGRAM2*

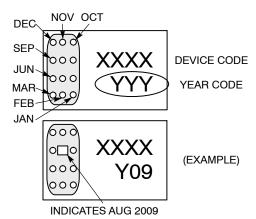
XXXX = Specific Device Code YYY = Year Code

= Specific Device Code

= Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present. Some products may not follow the Generic Marking.

CATHODE BAND MONTH CODING



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DESCRIPTION:	DSN2, 0.6X0.3, 0.4P, (0201)		PAGE 1 OF 1	

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^{*}For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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